

FQPF50N06

60V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 31A, 60V, $R_{DS(on)} = 0.022\Omega$ @ $V_{GS} = 10$ V
- Low gate charge (typical 31 nC)
- Low C_{rss} (typical 65 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | FQPF50N06 | Units |
|----------------|---|-------------|---------------------|
| V_{DSS} | Drain-Source Voltage | 60 | V |
| I_D | Drain Current - Continuous ($T_C = 25^\circ\text{C}$) - Continuous ($T_C = 100^\circ\text{C}$) | 31 | A |
| | | 21.9 | A |
| I_{DM} | Drain Current - Pulsed (Note 1) | 124 | A |
| V_{GSS} | Gate-Source Voltage | ± 25 | V |
| E_{AS} | Single Pulsed Avalanche Energy (Note 2) | 495 | mJ |
| I_{AR} | Avalanche Current (Note 1) | 31 | A |
| E_{AR} | Repetitive Avalanche Energy (Note 1) | 4.7 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | 7.0 | V/ns |
| P_D | Power Dissipation ($T_C = 25^\circ\text{C}$) - Derate above 25°C | 47 | W |
| | | 0.31 | W/ $^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Junction Temperature Range | -55 to +175 | $^\circ\text{C}$ |
| T_L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | 300 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Typ | Max | Units |
|-----------------|---|-----|------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | -- | 3.22 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | -- | 62.5 | $^\circ\text{C}/\text{W}$ |

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------------------------------|---|---|-----|------|------|---------------------|
| Off Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ | 60 | -- | -- | V |
| $\Delta BV_{DSS} / \Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\ \mu\text{A}$, Referenced to 25°C | -- | 0.06 | -- | V/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$ | -- | -- | 1 | μA |
| | | $V_{DS} = 48\text{ V}, T_C = 150^\circ\text{C}$ | -- | -- | 10 | μA |
| I_{GSSF} | Gate-Body Leakage Current, Forward | $V_{GS} = 25\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | 100 | nA |
| I_{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -25\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | -100 | nA |

On Characteristics

| | | | | | | |
|--------------|-----------------------------------|--|-----|-------|-------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$ | 2.0 | -- | 4.0 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS} = 10\text{ V}, I_D = 15.5\text{ A}$ | -- | 0.018 | 0.022 | Ω |
| g_{FS} | Forward Transconductance | $V_{DS} = 25\text{ V}, I_D = 15.5\text{ A}$ (Note 4) | -- | 19 | -- | S |

Dynamic Characteristics

| | | | | | | |
|------------|------------------------------|--|----|------|------|----|
| C_{iss} | Input Capacitance | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$ | -- | 1180 | 1540 | pF |
| C_{oss} | Output Capacitance | | -- | 440 | 580 | pF |
| C_{riss} | Reverse Transfer Capacitance | | -- | 65 | 90 | pF |

Switching Characteristics

| | | | | | | |
|--------------|---------------------|--|-------------|-----|-----|-----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 30\text{ V}, I_D = 25\text{ A},$ $R_G = 25\ \Omega$ | -- | 15 | 40 | ns |
| t_r | Turn-On Rise Time | | -- | 105 | 220 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | -- | 60 | 130 | ns |
| t_f | Turn-Off Fall Time | | (Note 4, 5) | -- | 65 | 140 |
| Q_g | Total Gate Charge | $V_{DS} = 48\text{ V}, I_D = 50\text{ A},$ $V_{GS} = 10\text{ V}$ | -- | 31 | 41 | nC |
| Q_{gs} | Gate-Source Charge | | -- | 8 | -- | nC |
| Q_{gd} | Gate-Drain Charge | | (Note 4, 5) | -- | 13 | -- |

Drain-Source Diode Characteristics and Maximum Ratings

| | | | | | | |
|----------|---|--|----|-----|-----|----|
| I_S | Maximum Continuous Drain-Source Diode Forward Current | -- | -- | 31 | A | |
| I_{SM} | Maximum Pulsed Drain-Source Diode Forward Current | -- | -- | 124 | A | |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0\text{ V}, I_S = 31\text{ A}$ | -- | -- | 1.5 | V |
| t_{rr} | Reverse Recovery Time | $V_{GS} = 0\text{ V}, I_S = 50\text{ A},$ $di_F / dt = 100\text{ A}/\mu\text{s}$ (Note 4) | -- | 52 | -- | ns |
| Q_{rr} | Reverse Recovery Charge | | -- | 75 | -- | nC |

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 600\ \mu\text{H}, I_{AS} = 31\text{ A}, V_{DD} = 25\text{ V}, R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 50\text{ A}, di/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\ \mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature